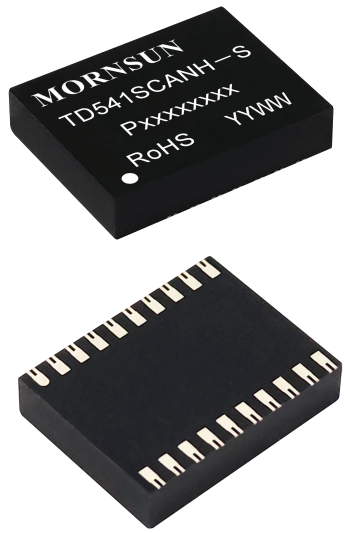
MORNSUN®

TD541SCANH-S
DFN package isolated CAN transceiver

Features

- Ultra-small, ultra-thin, chip scale DFN package
- Compliant with ISO11898-2 standard
- Integrate 5V efficiently power supply
- I/O power supply range supports 3.3V and 5V microprocessors
- High isolation to 5000VDC
- Bus-Pin ESD protection up to 15kV(HBM)
- Baud rate up to 1Mbps
- -40V to +40V bus fault protection
- >25kV/us CMTI
- TXD dominant time-out function
- Low communication delay
- The bus supports maximum 110 nodes
- Industrial operating ambient temperature range: -40℃ to +125℃
- AEC-Q100 experiment in progress
- EN62368 approval
- Moisture Sensitivity Level (MSL) 3
- Bottom PCB meets CTI Category II (400≤CTI<600)

Package



Applications

- Industrial automation, control, sensors and drive systems
- Building and greenhouse environmental control(HVAC) automation
- Security system
- Transport
- Medical treatment
- Telecommunication
- CAN Bus standard such as CAN open, Device Net, NMEA2000, ARNIC825, ISO11783, CAN Kingdom, CAN aerospace

Functional Description

TD541SCANH-S is a isolated CAN Bus transceiver, which is compliant with ISO11898-2 standard. Their logic side supports 3.3V and 5V logic level conversion.TD541SCANH-S integrate 5 V efficiently power. The TD541SCANH-S provide differential transmitting and receiving capability between the CANH protocol controller and the physical layer bus. It is capable of running at data rates of up to 1 Mbps. The device has the function of series line, over-voltage(-40V to 40V), ground loss protection and thermal shutdown so that it is especially suitable for working in harsh environment.

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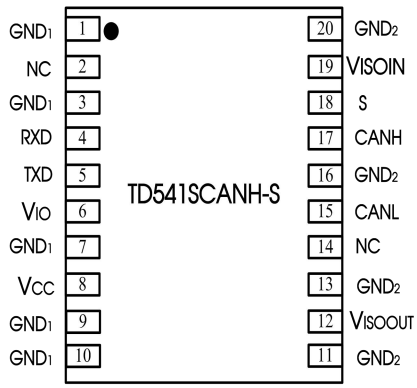
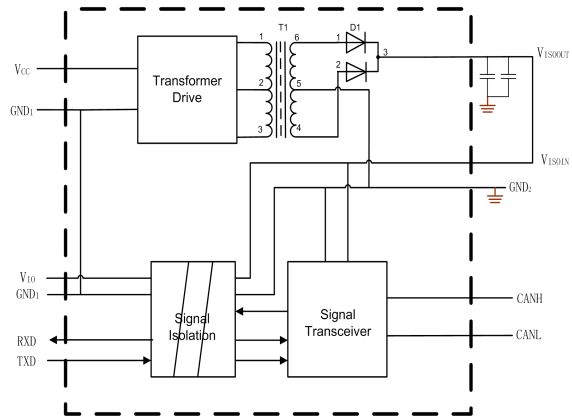
Pin Connection



Note：All GND_1 pins are internally connected;
All GND_2 pins are internally connected.

Internal Block Diagram



Function Table

Letter	Description
H	High-Level
L	Low-Level
X	Unrelated
Z	High Impedance

Table 1. Driver Function table

Inputs		Outputs		Bus State
TXD	S	CANH	CANL	
L	L (Or No Connection)	H	L	Dominant
H (Or No Connection)	X	Z	Z	Recessive
X	H	Z	Z	Recessive

Table 2. Receiver Function table

V_{ID}=CANH-CANL	RXD	Bus State
V_{ID}≥0.9V	L	Dominant
0.5< V_{ID}<0.9V	Uncertainty	Uncertainty
V_{ID}≤0.5V	H	Recessive
OPEN	H	Recessive

Pin Descriptions

Pin Number	Pin Name	Pin Functions
1	GND_1	Ground(Logic side)
2	NC	No connect
3	GND_1	Ground(Logic side)
4	RXD	Receiver output pin
5	TXD	Driver input pin
6	V_{IO}	Isolation power supply pin. By using 0.1uF ceramic capacitance ground GND_1
7	GND_1	Ground(Logic side)
8	V_{CC}	Power supply pin. By using 1uF ceramic capacitance ground GND_1
9	GND_1	Ground(Logic side)
10	GND_1	Ground(Logic side)
11	GND_2	Ground (Bus side)
12	V_{ISOOUT}	Insulation power output. By using 1uF ceramic capacitance ground GND_2. The pin needs to be connected to pin19 in application
13	GND_2	Ground (Bus Side)
14	NC	No connect
15	CANL	Low level CAN voltage input/output
16	GND_2	Ground (Bus side)
17	CANH	High level CAN voltage input/output
18	S	Ground Pin. In normal applied, this pin no connect or connect to ground GND_2
19	V_{ISOIN}	Insulation power input. By using 0.1uF ceramic capacitance ground GND_2. The pin needs to be connected to pin12 in application
20	GND_2	Ground (Bus side)

Absolute Maximum Ratings

General test conditions: Free-air, normal operating temperature range (unless otherwise specified).

Parameters	Unit
Supply voltage, V_{cc}	-0.3V to +5.6V
Digital input voltage (TXD, RXD)	-0.3V to +6V
Bus voltage (CANH, CANL)	-40 to 40V
Receiver output current	-15 to 15mA
Operating temperature range	−40°C to +125°C
Storage temperature range	−50°C to +125°C
Reflow soldering temperature	Peak temp. ≤250℃, maximum duration ≤60s at 217℃. Please also refer to IPC/JEDEC J-STD-020D. 3.

Important: Exposure to absolute maximum rated conditions for an extended period may severely affect the device reliability, and stress levels exceeding the “Absolute Maximum Ratings” may result in permanent damage.

Recommended Operating Conditions

Parameters			Min.	Nom.	Max.	Unit
V_{CC}	Power supply		4.5	5	5.5	V
V_{IO}	Power supply(Logic Side)		2.75		5.25	V
V_I or V_{IC}	Voltage at any bus terminal (differential mode)		–40		40	V
V_{IH}	High-level input voltage(TXD)		2		5.5	V
V_{IL}	Low-level input voltage(TXD)		0		0.8	V
T_A	Operating temperature range		-40		125	°C
I_{CC}	Recessive mode current			20	35	mA
I_{CC}	Working current	V_{CC}= 5V, R_L= 60Ω; TXD signal, f=500kHz; Duty=50%		35	55	mA
	Signaling rate		40		1000	kbps

Electrical Characteristics

General test conditions and V_{CC}=V_{IO}= 5V, Ta = 25℃ (unless otherwise specified).

Parameters		Conditions	Min.	Nom.	Max.	Unit
Driver						
$\|V_{O(D)}\|$	Dominant CANH output voltage	Figure 8 V_{TXD} = 0 V, R_L = 60 Ω	2.75	3.5	4.5	V
	Dominant CANL output voltage		0.5	1.5	2.25	
$V_{O(R)}$	Recessive bus voltage	Figure 8 V_{TXD} = 2 V, R_L= 60 Ω	2	2.5	3	V
$V_{OD(D)}$	Dominant differential output voltage	Figure 8 V_{TXD} = 0 V, t < $t_{to(dom)TXD}$, V_{CC}=4.75 V to 5.25 V, R_L = 50 to 65 Ω	1.5		3	V
$V_{OD(R)}$	Recessive differential output voltage	Figure 8 V_{TXD} = 5 V, R_L= 60 Ω	–0.12		0.012	V
		V_{TXD} = 5 V, No load	–0.5		0.05	
I_{IH}	TXD High-level input current	V_{TXD} =2 V	2			mA
I_{IL}	TXD Low-level input current	V_{TXD} =0.8 V	2			mA
R_{TXD}	Internal TXD Pull up Resistor			9.1		kΩ
Receiver						
V_{IT+}	Positive-going input threshold voltage	Figure 11		750	900	mV
$V_{IT–}$	Negative-going input threshold voltage		500	650		mV
V_{hys}	Hysteresis voltage (V_{IT+} - $V_{IT–}$)			120		mV
V_{OH}	High-level output voltage	I_{OH} = –4 mA, Figure 9	V_{IO} – 0.4	V_{IO} – 0.2		V
		I_{OH} = –20 uA, Figure 9	V_{IO} – 0.4	V_{IO} – 0.2		
V_{OL}	Low-level output voltage	I_{OL} = 4 mA, Figure 9		0.2	0.4	V
		I_{OL} = 20 uA, Figure 9		0.2	0.4	
C_I	Input capacitance to ground (CANH or CANL)	V_{TXD} = 5 V, V_I = 0.4 sin (4E6 π t) + 2.5 V		13		pF
C_{ID}	Differential input capacitance	V_{TXD} = 5 V, V_I = 0.4 sin (4E6 π t)		5		pF
R_{ID}	Differential input resistance	V_{TXD} = 5 V	15	30	40	kΩ
R_{IN}	Input resistance (CANH or CANL)	V_{TXD} = 5 V	10		100	kΩ
$R_{I(m)}$	Input resistance matching: [1 – $R_{IN(CANH)}$ / $R_{IN(CANL)}$] × 100%	V_{CANH} = V_{CANL}	–3%	0%	3%	
CE	CISPR32/EN55032	Figure 15	CLASS B			
RE	CISPR32/EN55032	Figure 15	CLASS A			
ESD	HBM	CANH, CANL pin to GND			±15	kV
		Other pins			±2	kV
	Contact	CANH, CANL pin to GND			±2	kV
EFT	IEC61000-4-4: Perf. Criteria B	CANH, CANL and GND			±2	kV
Surge	IEC61000-4-5: Perf. Criteria B	CANH, CANL and GND(Common Mode)			±2	kV
	Isolation voltage	TD541SCANH-S			5000	VDC
	Insulation resistance		1000			MΩ
	Isolation capacitor			3		pF
CMTI	Common Mode Transient Immunity	V_{TXD} = V_{CC} or 0 V, V_{CM} = 1 kV, transient magnitude = 800 V	25			kV/us

Transmission Characteristics

General test conditions and V_{CC}=V_{IO}= 5V, Ta = 25℃ (unless otherwise specified).

Parameters		Conditions	Min.	Nom.	Max.	Unit
t_{onTxD}	Propagation delay TXD On to bus active	R_L = 60 Ω, C_L = 100 pF, see Figure 10 and Figure 12		80	150	ns
t_{offTxD}	Propagation delay TXD Off to bus inactive			80	200	ns
t_{onRxD}	Propagation delay RXD On to receiver active			60	300	ns
t_{offRxD}	Propagation delay RXD Off to receiver inactive			60	250	ns
t_{TXD_DTO}	Dominant time-out time	C_L=100 pF	0.3		12	ms

Physical Specifications

Parameters	Value	Unit
Weight	0.8(Typ.)	g

Typical Performance Curves

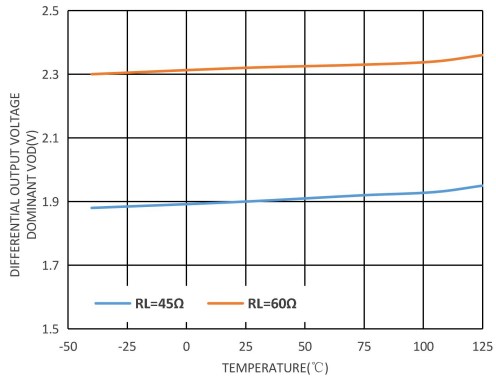


Figure 1. Drive differential output voltage dominant VS Temperature

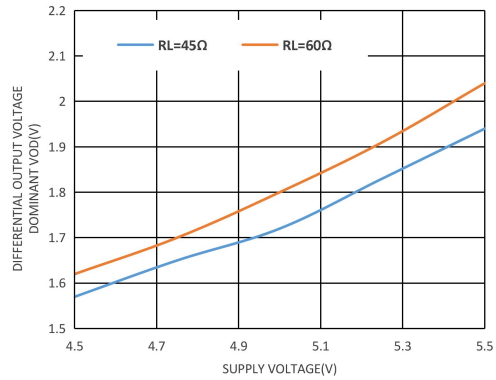


Figure 2. Drive differential output voltage dominant VS Working voltage

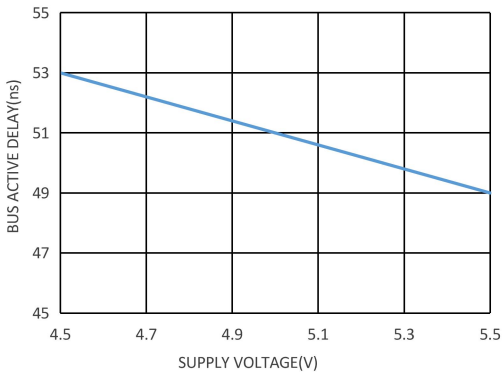


Figure 3. Propagation delay from TXD On to bus active VS Working voltage

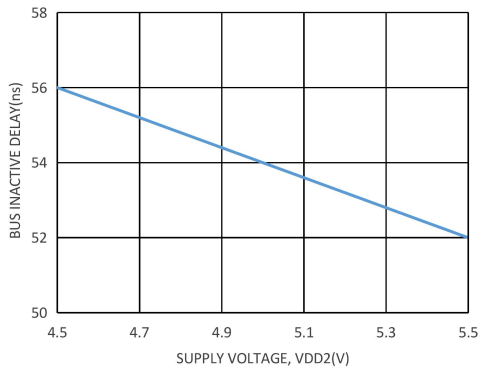


Figure 4. Propagation delay from TXD Off to bus inactive VS Working voltage

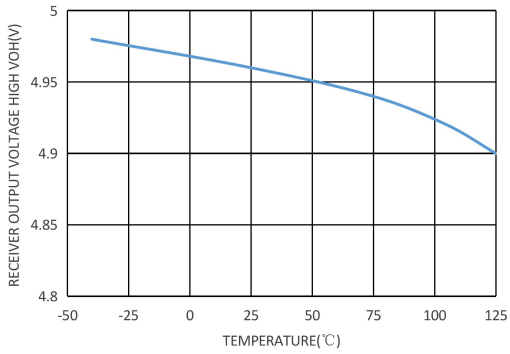


Figure 5. Receiver output voltage VS Temperature

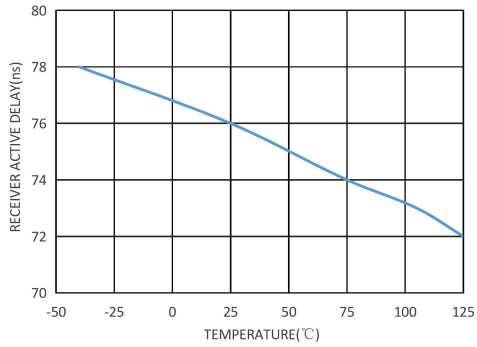


Figure 6. Receiver active delay VS Operating Temperature

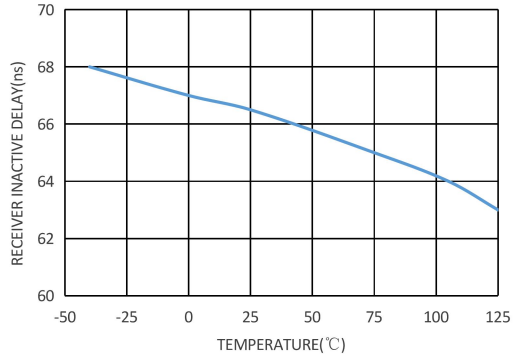


Figure 7. Receiver inactive delay VS Operating Temperature

Test Circuits

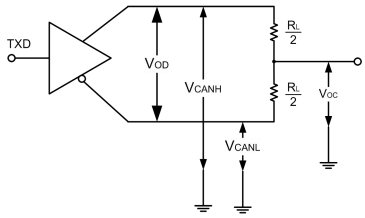


Figure 8. Driver test circuit

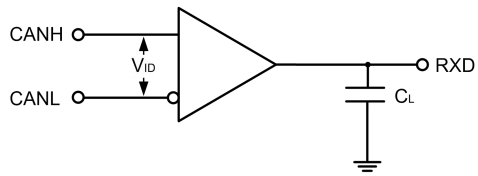


Figure 9. Receiver test circuit

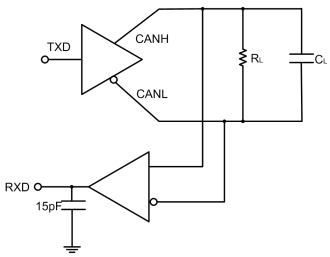


Figure 10. Switching characteristics test circuit

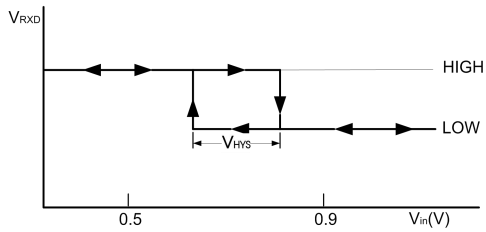


Figure 11. Receiver input hysteresis

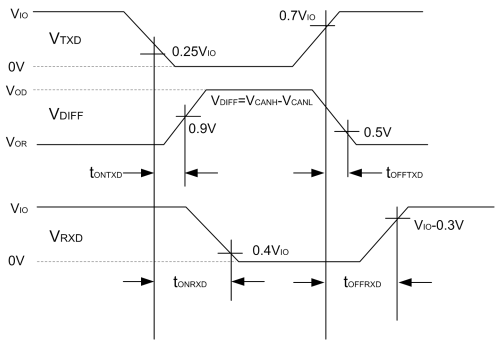


Figure 12. Drive and receiver propagation delay

Detailed Description

TD541SCANH-S is a CAN of a style of separation transceiver with the ability of differential signal transmission between the bus and CAN protocol controller, it the inner integration insulate DC/DC power supply. which is compliant with ISO11898-2 standard.

Short-circuit protection: TD541SCANH-S has current-limiting protection to prevent the drive circuit from short-circuiting to positive and negative supply voltages. The power dissipation increases when a short circuit occurs. The short-circuit protection function protects the driver stage from damage.

Over-temperature protection: TD541SCANH-S has over-temperature protection. When the junction temperature exceeds 160°C, the current in the driver stage will decrease. Because the drive tube is the primary energy consuming component, current reduction can reduce power consumption and reduce chip temperature. At the same time, the rest of the chip remains functional.

Dominant time-out function: TD541SCANH-S has dominant time-out function to prevent if the pin TXD is forced to a permanent low level due to a hardware or software application failure, the built-in TXD dominant timeout timer circuit prevents the bus line from being driven to a permanent dominant state (blocking all network traffic). The timer is triggered by the negative edge on pin TXD.

If the low level on pin TXD lasts longer than the internal timer value (t_{TXD_DTO}), the transmitter will be disabled and the drive bus will enter a recessive state. The timer is reset by the positive edge on pin TXD.

Application circuit

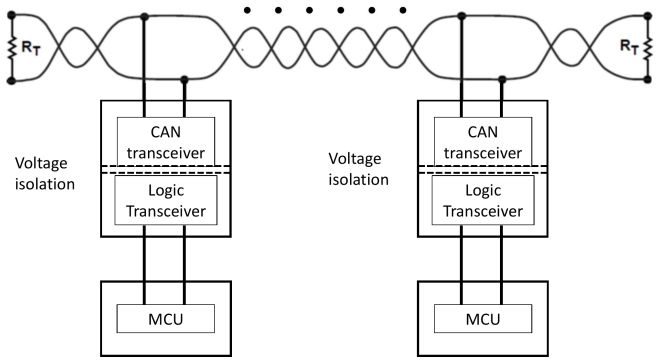


Figure13. Typical application circuit

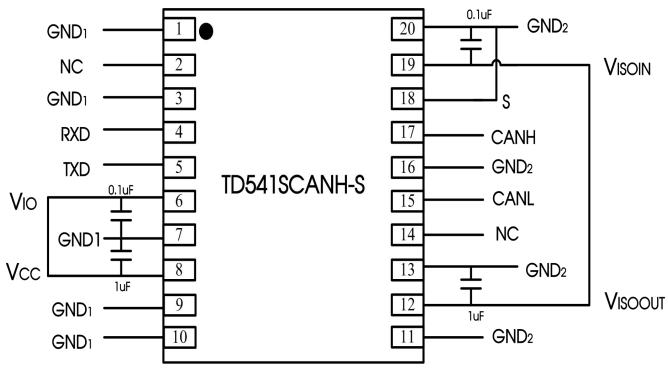


Figure14. Type PCB layout

In General, Vcc and Vlo can be shorted(Figure 14) .If the controller doesn't support 5V signal input, it can power 3.3V for Vlo.
When the module works in normal condition connect the S foot to GND1.

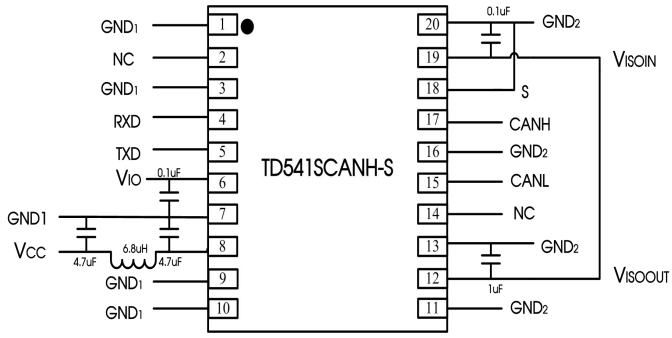


Figure15. EMI Recommended circuit

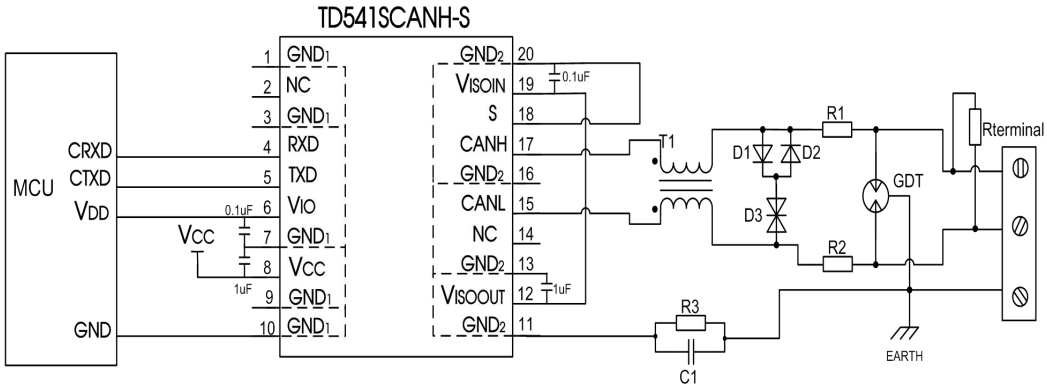


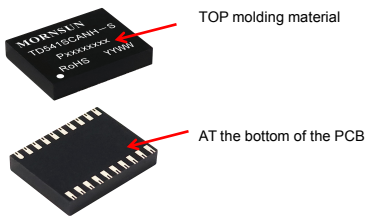
Figure16. Port protection circuit for harsh environments

Recommended components and values:

Component	Recommended part, value	Component	Recommended part, value
R3	1MΩ	D1、D2	1N4007
C1	1nF, 2kV	D3	SMBJ30CA
T1	ACM2520-301-2P	$R_{terminal}$	120Ω
GDT	B3D090L	R1、R2	2.7Ω/2W

When the module is used in applications with harsh environment, it can be susceptible to large energy like lightning strike, etc. in which case, it is essential to add an adequate protection circuit to the CAN signal ports to protect the system from failure and maintain a reliable bus communication. Figure 16 provides a recommended protection circuit design for high-energy lightning surges, with a degree of protection related to the selected protection device. Parameter description lists a set of recommended circuit parameters, which can be adjusted according to the actual application situation. Also, when using the shielded cable, the reliable single-point grounding of the shield must be achieved.

Note: The recommended components and values is a general guideline only and must be verified for the actual user's application. We recommended using PTC's for R1 and R2 and to use fast recovery diodes for D1 and D2.



The top molding material of the product meets CTI category I (600≤CTI); Bottom PCB plate meets CTI category I I (400≤CTI<600).

Using Suggests

① Power isolation V_{ISOOUT} need through a series of capacitors connected to the output pin V_{ISOIN}, the power supply is not recommended for other purposes, otherwise it may cause the bus voltage did not meet the requirements of communication, causes the communication failure.

② Hot-swap is not supported.

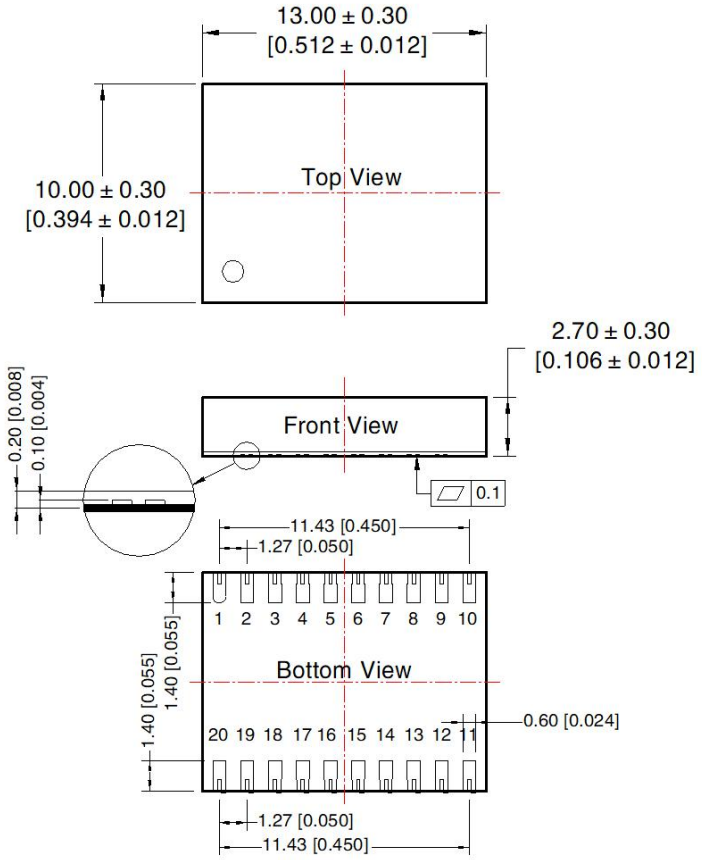
③ If the external input of TXD is insufficient, the pull-up resistor should be added according to the situation.

④ Refer to *IPC 7093* for the welding process design of this product. For detailed operation guidance, please refer to *Hot Air Gun Welding Operation Instruction for DFN Package Product* or *Welding Operation Instruction for DFN Package Product*.

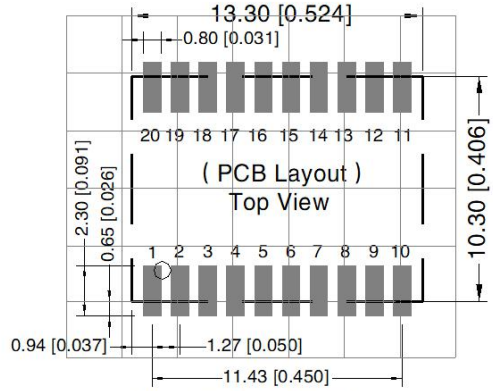
Ordering Information

Part number	Package	Number of pins	Product marking	Tape & Reel
TD541SCANH-S	DFN	20	TD541SCANH-S	300/REEL

THIRD ANGLE PROJECTION

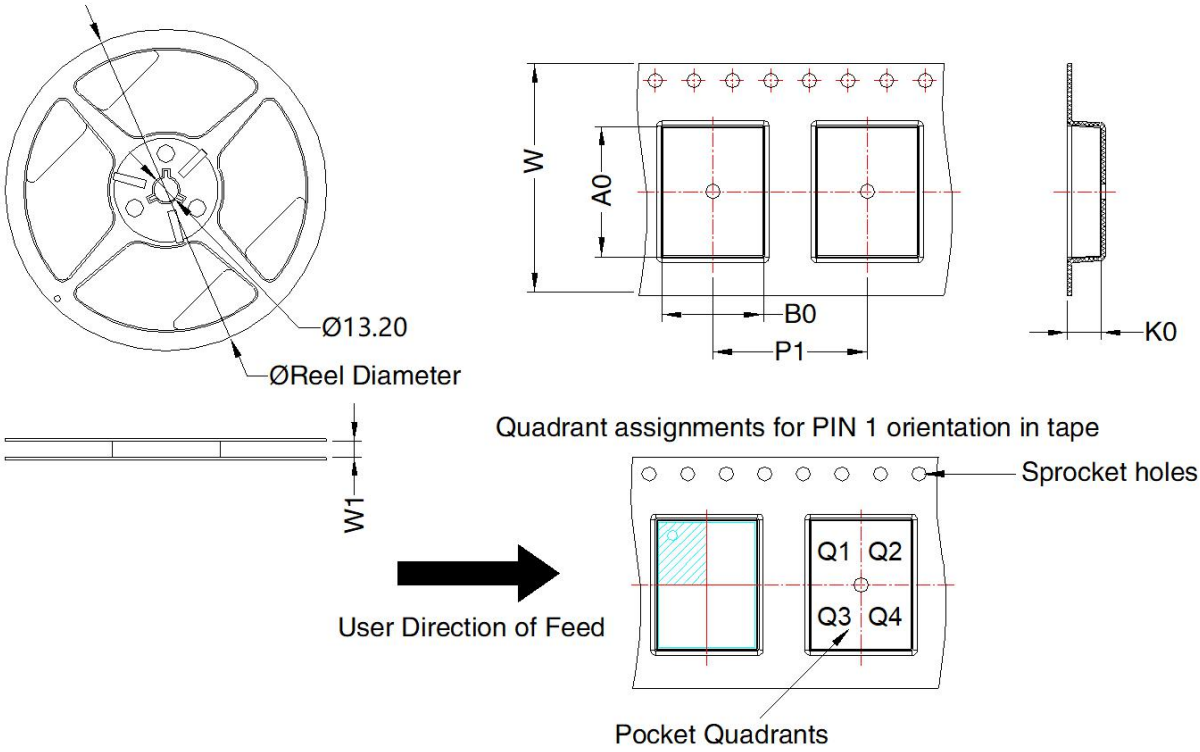


Note:
Unit: mm[inch]
Pin diameter tolerances: ± 0.10[± 0.004]



Note: Grid 2.54*2.54mm

Pin–Out			
Pin	Mark	Pin	Mark
1	GND_1	11	GND_2
2	NC	12	V_{ISOOUT}
3	GND_1	13	GND_2
4	RXD	14	NC
5	TXD	15	CANL
6	V_{IO}	16	GND_2
7	GND_1	17	CANH
8	V_{CC}	18	S
9	GND_1	19	V_{ISOIN}
10	GND_1	20	GND_2



Device	Package Type	Pin	MPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TD541SCANH-S	DFN 10x13	20	300	180.0	24.4	13.52	10.52	3.5	16.0	24.0	Q1

MORNSUN Guangzhou Science & Technology Co., Ltd.
Address: No. 5, Kehui St. 1, Kehui Development Center, Science Ave., Guangzhou Science City, Huangpu District, Guangzhou, P. R. China
Tel: 86-20-38601850 Fax: 86-20-38601272 E-mail: info@mornsun.cn www.mornsun-power.com